October 22 (Thu.), 2026

[Oral 11] CMP Consumables (II)

11:25-12:45

International Conference Hall (B1F)

● Session Chair: Andy Tuan (Linx Consulting Inc., Taiwan)

11:25-11:45 [Oral 11-1]	The Interconnect Advantage: CMP Powering AI and HBM Ping Tzeng, Jingzhi Chen (Merck, Taiwan), and Hongjun Zhou (The Electronics Business of Merck KGaA, Germany)
11:45-12:05 [Oral 11-2]	Study on the Mechanism of unCMP Caused by Plastic Deformation of the Head Membrane in CMP Equipment and Its Improvement KyongKyu Myong, Jubong Lee, Younggeun Lee, Yoo-Yong Lee, Ki Ho Bae, and Hoyoung Kim (Samsung Electronics Co., Ltd., Korea)
12:05-12:25 [Oral 11-3]	Identifying the Origin of Small Particle Defects in Oxide Chemical Mechanical Planarization Seungmoon Choi, Hyeonjeong Lee, Hyunho Kim, Junil Cho, and Taesung Kim (Sungkyunkwan Univ., Korea)
12:25-12:45 [Oral 11-4]	New Particle and Chemistry Technology for Metals IC CMP Slurries Yu Yu Chou, Howl Hsu (Entegris Co., Ltd., Taiwan), Brian Reiss, and Na Zhang (Entegris Inc., USA)